

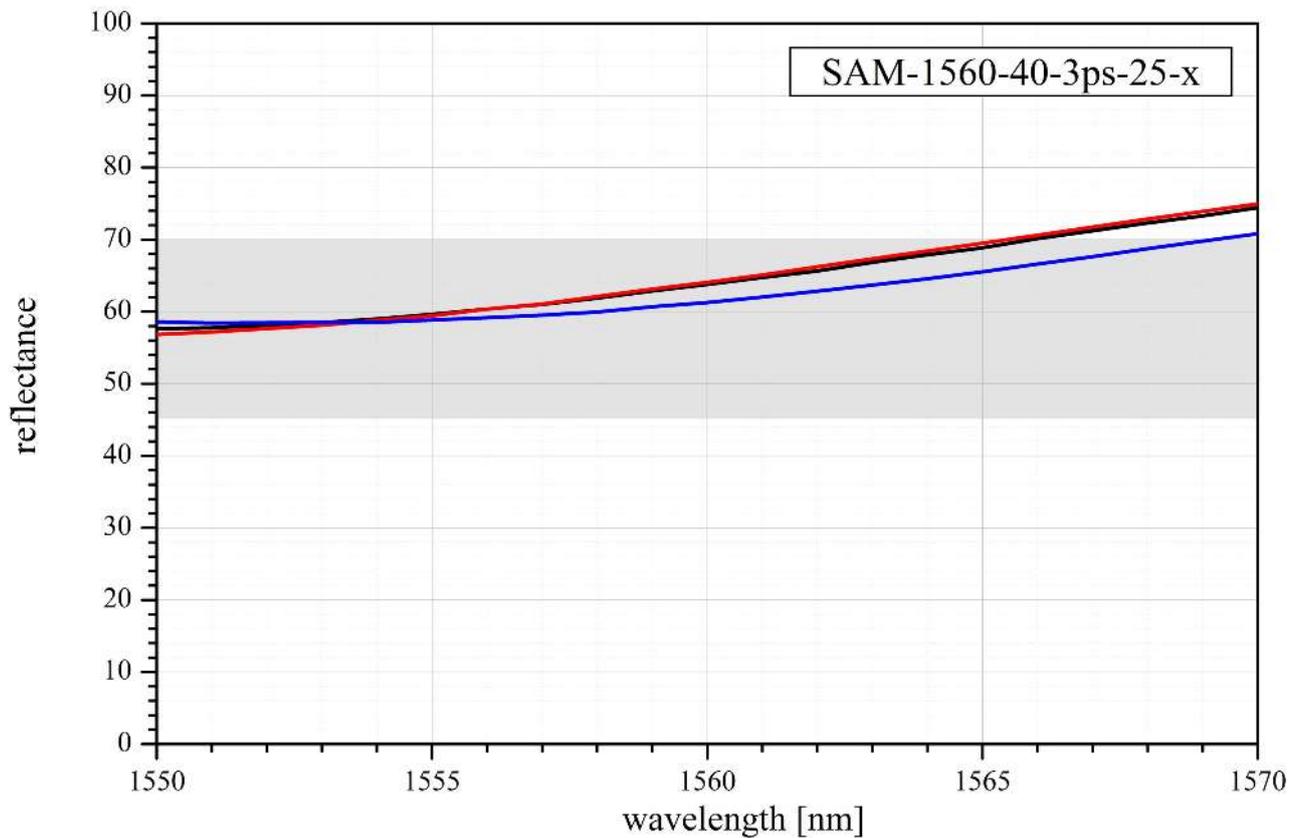
### SAM™ Data Sheet SAM-1560-40-3ps-25-x

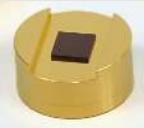
	Minimum	Typical Value	Maximum
Operational wavelength $\lambda$		1560 nm	
High reflection band	1550 nm		1570 nm
Absorbance $A$ <sup>1</sup>	30%	40%	55%
Modulation depth $\Delta R$ <sup>1</sup>	15 %	20 %	
Saturation fluence $\Phi_{\text{sat}}$ <sup>1</sup>	20 $\mu\text{J}/\text{cm}^2$	25 $\mu\text{J}/\text{cm}^2$	30 $\mu\text{J}/\text{cm}^2$
Relaxation time constant $\tau$ <sup>1</sup>	1 ps	3 ps	6 ps
Damage threshold $\Phi$		1 $\text{mJ}/\text{cm}^2$	
Absorber Peak Temperature			150°C <sup>2</sup>
Chip thickness	425 $\mu\text{m}$	450 $\mu\text{m}$	475 $\mu\text{m}$
Protection	SAM is protected with a dielectric front layer		

<sup>1</sup> at operation wavelength

<sup>2</sup> Make sure that this temperature is not exceeded in pulsed operation shortly after the optical pulse.

#### Typical unsaturated spectral reflectance measured at room temperature with 6° AOI



Mounting Options SAM-1560-40-3ps-25-x	Description
<b>x = 4.0-0</b>	Single chip, unmounted, chip size 4.0mm x 4.0mm
<b>x = 1.0b-0</b>	Batch of 4 unmounted chips, chip size 1.0mm x 1.0mm
<b>x = 1.3b-0</b>	Batch of 4 unmounted chips, chip size 1.3mm x 1.3mm
<b>x = 4.0-12.7g-c / 4.0-12.7g-e</b>	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 12.7 mm $\varnothing$
<b>x = 4.0-25.0g-c / 4.0-25.0g-e</b>	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.0 mm $\varnothing$
<b>x = 4.0-25.4g-c / 4.0-25.4g-e</b>	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.4 mm $\varnothing$
<b>x = 4.0-12.7s-c / 4.0-12.7s-e</b>	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 12.7 mm $\varnothing$
<b>x = 4.0-25.0s-c / 4.0-25.0s-e</b>	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.0 mm $\varnothing$
<b>x = 4.0-25.4s-c / 4.0-25.4s-e</b>	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.4 mm $\varnothing$
<b>x = 4.0-25.0w-c / 4.0-25.0w-e</b>	chip size 4.0mm x 4.0mm, soldered on a water cooled copper heat sink with 25.0 mm diameter
<b>x = 4.0-25.4h-c / 4.0-25.4h-e</b>	chip size 4.0mm x 4.0mm, thin film soldered on a water cooled copper heat sink with 25.0 mm diameter for high power application
<b>-c</b> Center mounting 	<b>-e</b> Edge mounting 
<b>x = FC/(A)PC-SMF</b>	mounted on a 1 m long single mode fiber - FC/PC connector: x = FC/PC-SMF - FC/APC connector: x = FC/APC-SMF available fiber types: SMF28
<b>x = FC/(A)PC-PMF</b>	mounted on a 1 m long polarization maintaining single mode fiber - FC/PC connector: x = FC/PC-PMF - FC/APC connector: x = FC/APC-PMF available fiber types: SM15-PS-U25D
Other chip dimensions are also possible, please ask.	